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Date: November 12, 2003

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Re: 10/059,686

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From: David M. Sigmond

TECHNOLOGY

Copies of the following documents are attached:

1. Response filed April 25, 2003 (25 pages)
2. Return Postcard establishing PTO receipt of Response

Please let me know if I can assist further.

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TOTAL NUMBER OF PAGES: 27 (Including This Page)
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Cheng-Lien Chiang
Assignee: Bridge Semiconductor Corporation
Title: METHOD OF MAKING A SEMICONDUCTOR PACKAGE DEVICE THAT INCLUDES A CONDUCTIVE TRACE WITH RECESSED AND NON-RECESSED PORTIONS
Serial No.: 10/059,686 Filed: January 29, 2002
Examiner: Zarncke, D. Group Art Unit: 2827
Atty. Docket No.: BDG005-1

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

RESPONSE

In response to the Office Action dated April 18, 2003, please amend the application as follows.

In the Title

The Title has been replaced with:

METHOD OF MAKING A SEMICONDUCTOR PACKAGE DEVICE THAT INCLUDES A CONDUCTIVE TRACE WITH RECESSED AND NON-RECESSED PORTIONS

In the Specification

Replace the paragraph at page 10, lines 5-14 with the following paragraph:

FIGS. 1A and 1B are top and bottom perspective views, respectively, of semiconductor chip 110 which is an integrated circuit in which various transistors, circuits, interconnect lines and the like are formed (not shown). Chip 110 includes opposing major surfaces 112 and 114